

ST-170 AlN SUBSTRATES

ALUMINUM NITRIDE

Aluminum nitride (AlN) provides the high performance electrical and thermal properties of beryllia (BeO) at a more economical cost and without BeO's toxicity concerns.

Sienna ST-170 AlN substrates offer:

- High thermal conductivity
- Thermal expansion that closely matches that of Si, SiC, and GaN over a wide temperature range
- No-toxicity - Aluminum Nitride poses no special disposal requirements
- Reliable metallization performance
- Available with as-fired or lapped surfaces that are ideal for thick film application
- Significant cost/performance advantage
- Standard sizes (inch) include:
 - 2x2x0.025
 - 4x4x0.025
 - 4.5x4.5x0.015
 - 4.5x4.5x0.040

These attributes make Sienna ST-170 AlN substrates the best choice for solving thermal management problems in power electronics and microwave applications. ST-170 AlN is the ideal electronic substrate for high power and high frequency applications including:

- Power Transistors and Rectifiers
- Power Supplies
- Chip Carriers
- Heat Spreaders



Sienna's technical team is ready to help you implement Aluminum Nitride in your current and next generation of products. Contact us for applications assistance, and for fast prototyping and production needs.

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 **SIENNA**
TECHNOLOGIES Inc.®
providing solutions through advanced materials

ST-170 AlN SUBSTRATES

AlN PROPERTIES

| | ST-170 |
|--|---|
| Color | Light Gray |
| Density, g/cm³ | >3.30 |
| Thermal Conductivity, W/m·K | 170±10 |
| Heat Capacity @ RT, J/g·K | 0.736 |
| Thermal Expansion Coefficient, X10⁻⁶/°C 25°C - 400°C | 4.4 |
| Dielectric Strength, kV/mm | ≥25 |
| Volume Resistivity, Ohm-cm | >10 ¹³ |
| Dielectric Constant @1 MHz | 8.4 |
| Loss Tangent @1 MHz | 0.002 |
| Surface Roughness, Ra, μm As-fired Lapped | 0.6 0.4 |
| Camber, mm/mm | 0.003 (typical) |
| Flexural Strength, MPa | 350 |
| Elastic Modulus, GPa | 320 |
| Poisson's Ratio | 0.24 |
| Hardness, GPa | 12 |
| Application | High thermal conductivity, chip carriers/substrates |

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